

SRC Research Needs in Computer-Aided Design Tools

November 2007

The Semiconductor Research Corporation's Global Research Collaboration is seeking innovative research leading to significant advances in **System-Level/High-Level Tools** and **Logic/Physical Design Tools**. Needs categories of interest to the members are listed in the two tables below.

In accord with the SRC strategic plan and member development of this needs document, the Computer-Aided Design and Test Sciences area is placing renewed emphasis on system-level and high-level design. To this end, as we conduct our usual solicitation for logic/physical design tools, we introduce the new system-level, high-level design category. This stresses tools to facilitate higher-level design, and may include system-level verification and test tools.

Areas that SRC GRC member companies anticipate sustained or increased efforts in the coming five-year period include resilient design (with awareness of variability and statistical effects and the manufacturing interface), analog/mixed-signal/RF design tools, and tools for SoC and SiP designs. There is also member interest in areas where research is needed to enhance design automation tools to address technology advances such as 3-D, FinFET, double gate, etc.

Several themes important to SRC GRC member companies pervade the categories and subcategories below:

- Tools taking advantage of **parallel/multi-core platforms**
- Power aware/**power reduction** tools at all levels
- Tools incorporating **robust optimization** techniques

CADTS Research Needs: System-Level/High-Level Tools

2007 System-Level/High-Level Tools Needs Categories	
H1	Tools for Design Space Exploration
H1.1	Early design space exploration tools, including evaluation and estimation of architectural paradigms, partitioning for mixed-signal, SoC and SiP (including 3-D)
H1.2	Tools for hardware/software partitioning and support re-configurability and repair
H1.3	Tools for system-level tradeoff analysis incorporating power, yield, thermal, timing, performance, etc.
H2	Tools for System-Level Design
H2.1	Behavioral and system-level design and synthesis tools (pre-RTL), including incorporation of hard/soft IP blocks
H2.2	Tools for the design of multi-core systems
H2.3	High-level SoC/SiP design tools, including analog/RF/mixed-signal sub-systems
H2.4	Design tools enabling system-level to/from lower-level communication and abstraction
H3	Tools for System-Level Verification and Test
H3.1	Tools for system level validation/verification of correctness, performance and robustness
H3.2	System-level design for test and post-silicon validation
H4	Tools for System Design Robustness
H4.1	Design tools that implement reliable resilient systems with non-functional or unreliable components
H4.2	Design tools for systems using components with significant variations
H4.3	DFM/DFR tools at higher levels in the design flow
H5	System Power Optimization Tools
H5.1	Efficient system-level power management tools
H5.2	Tools for efficient system-level control of power and elimination of hot spots
H5.3	Tools that optimize supply voltage, frequency and Vt domains at the system level

CADTS Research Needs: Logic/Physical Design Tools

2007 Logic/Physical Design Tools Needs Categories	
L1	Core/IP Design Tools
L1.1	Advanced logic synthesis, including for 3D, variable back bias, multiple voltages, etc.
L1.2	Fundamental/significant place/route improvements
L1.3	Tools for clock/power distribution/optimization, including those enabling alternatives to conventional synchronous clocking schemes
L1.4	Tools addressing power/thermal considerations
L1.5	Memory design and analysis tools
L2	Analog/Mixed Signal Design Tools
L2.1	Analog synthesis
L2.2	Tools for automation of design of passives (MEMS, inductors, capacitors)
L2.3	Advanced analog simulation
L2.4	Multiple voltage analog design tools
L3	Design/Manufacturing Interface Tools
L3.1	Yield-aware and yield optimization tools including resolution enhancement techniques
L3.2	Design tools exploiting lithography/mask knowledge
L3.3	Tools mitigating noise, interference effects (inductance, skin effect, high frequencies, signal integrity, coupling)
L3.4	Design closure tools comprehending the effects of manufacturing variability
L3.5	Tools enabling defect-tolerant designs resistant to static and dynamic faults (probabilistic design, single-event upset awareness, etc.)
L4	Tools for Diverse Technologies and Applications
L4.1	Tools for design using innovative CMOS nanostructures
L4.2	Logic/physical/circuit design tools for diverse applications